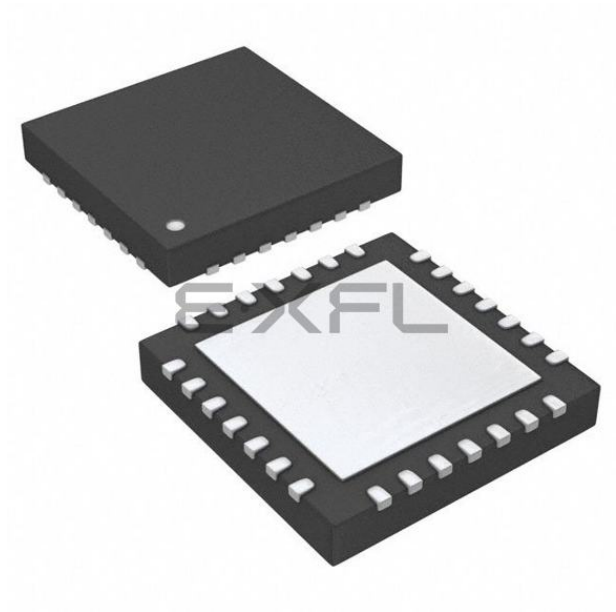

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	25
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	368 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 11x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f726-e-ml

TABLE 1: 28-PIN PDIP/SOIC/SSOP/QFN/UQFN SUMMARY (PIC16F722/723/726/PIC16LF722/723/726)

I/O	28-Pin PDIP, SOIC, SSOP	28-Pin QFN, UQFN	A/D	Cap Sensor	Timers	CCP	AUSART	SSP	Interrupt	Pull-Up	Basic
RA0	2	27	AN0	—	—	—	—	$\overline{SS}$(3)	—	—	VCAP(4)
RA1	3	28	AN1	—	—	—	—	—	—	—	—
RA2	4	1	AN2	—	—	—	—	—	—	—	—
RA3	5	2	AN3/VREF	—	—	—	—	—	—	—	—
RA4	6	3	—	CPS6	T0CKI	—	—	—	—	—	—
RA5	7	4	AN4	CPS7	—	—	—	$\overline{SS}$(3)	—	—	VCAP(4)
RA6	10	7	—	—	—	—	—	—	—	—	OSC2/CLKOUT/VCAP(4)
RA7	9	6	—	—	—	—	—	—	—	—	OSC1/CLKIN
RB0	21	18	AN12	CPS0	—	—	—	—	IOC/INT	Y	—
RB1	22	19	AN10	CPS1	—	—	—	—	IOC	Y	—
RB2	23	20	AN8	CPS2	—	—	—	—	IOC	Y	—
RB3	24	21	AN9	CPS3	—	CCP2(2)	—	—	IOC	Y	—
RB4	25	22	AN11	CPS4	—	—	—	—	IOC	Y	—
RB5	26	23	AN13	CPS5	T1G	—	—	—	IOC	Y	—
RB6	27	24	—	—	—	—	—	—	IOC	Y	ICSPCLK/ICDCLK
RB7	28	25	—	—	—	—	—	—	IOC	Y	ICSPDAT/ICDDAT
RC0	11	8	—	—	T1OSO/T1CKI	—	—	—	—	—	—
RC1	12	9	—	—	T1OSI	CCP2(2)	—	—	—	—	—
RC2	13	10	—	—	—	CCP1	—	—	—	—	—
RC3	14	11	—	—	—	—	—	SCK/SCL	—	—	—
RC4	15	12	—	—		—	—	SDI/SDA	—	—	—
RC5	16	13	—	—	—	—	—	SDO	—	—	—
RC6	17	14	—	—	—	—	TX/CK	—	—	—	—
RC7	18	15	—	—	—	—	RX/DT	—	—	—	—
RE3	1	26	—	—	—	—	—	—	—	Y(1)	$\overline{MCLR}$/VPP
—	20	17	—	—	—	—	—	—	—	—	VDD
—	8,19	5,16	—	—	—	—	—	—	—	—	VSS

Note 1: Pull-up enabled only with external $\overline{MCLR}$ Configuration.
2: RC1 is the default pin location for CCP2. RB3 may be selected by changing the CCP2SEL bit in the APFCON register.
3: RA5 is the default pin location for $\overline{SS}$. RA0 may be selected by changing the SSSEL bit in the APFCON register.
4: PIC16F724/727/PIC16LF724/727 devices only.

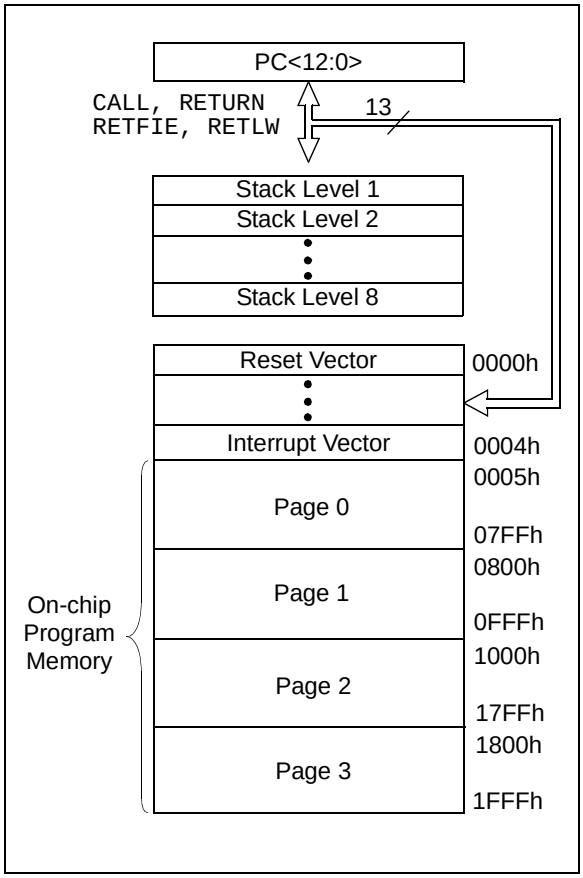
Note: The PIC16F722/3/4/6/7 devices have an internal low dropout voltage regulator. An external capacitor must be connected to one of the available VCAP pins to stabilize the regulator. For more information, see **Section 5.0 "Low Dropout (LDO) Voltage Regulator"**. The PIC16LF722/3/4/6/7 devices do not have the voltage regulator and therefore no external capacitor is required.

TABLE 1-1: PIC16(L)F722/3/4/6/7 PINOUT DESCRIPTION (CONTINUED)

Name	Function	Input Type	Output Type	Description
RB4/AN11/CPS4	RB4	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	AN11	AN	—	A/D Channel 11 input.
	CPS4	AN	—	Capacitive sensing input 4.
RB5/AN13/CPS5/T1G	RB5	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	AN13	AN	—	A/D Channel 13 input.
	CPS5	AN	—	Capacitive sensing input 5.
	T1G	ST	—	Timer1 Gate input.
RB6/ICSPCLK/ICDCLK	RB6	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	ICSPCLK	ST	—	Serial Programming Clock.
	ICDCLK	ST	—	In-Circuit Debug Clock.
RB7/ICSPDAT/ICDDAT	RB7	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	ICSPDAT	ST	CMOS	ICSP™ Data I/O.
	ICDDAT	ST	—	In-Circuit Data I/O.
RC0/T1OSO/T1CKI	RC0	ST	CMOS	General purpose I/O.
	T1OSO	XTAL	XTAL	Timer1 oscillator connection.
	T1CKI	ST	—	Timer1 clock input.
RC1/T1OSI/CCP2	RC1	ST	CMOS	General purpose I/O.
	T1OSI	XTAL	XTAL	Timer1 oscillator connection.
	CCP2	ST	CMOS	Capture/Compare/PWM2.
RC2/CCP1	RC2	ST	CMOS	General purpose I/O.
	CCP1	ST	CMOS	Capture/Compare/PWM1.
RC3/SCK/SCL	RC3	ST	CMOS	General purpose I/O.
	SCK	ST	CMOS	SPI clock.
	SCL	I^2C	OD	I^2C clock.
RC4/SDI/SDA	RC4	ST	CMOS	General purpose I/O.
	SDI	ST	—	SPI data input.
	SDA	I^2C	OD	I^2C data input/output.
RC5/SDO	RC5	ST	CMOS	General purpose I/O.
	SDO	—	CMOS	SPI data output.
RC6/TX/CK	RC6	ST	CMOS	General purpose I/O.
	TX	—	CMOS	USART asynchronous transmit.
	CK	ST	CMOS	USART synchronous clock.
RC7/RX/DT	RC7	ST	CMOS	General purpose I/O.
	RX	ST	—	USART asynchronous input.
	DT	ST	CMOS	USART synchronous data.
RD0/CPS8	RD0	ST	CMOS	General purpose I/O.
	CPS8	AN	—	Capacitive sensing input 8.
RD1/CPS9	RD1	ST	CMOS	General purpose I/O.
	CPS9	AN	—	Capacitive sensing input 9.
RD2/CPS10	RD2	ST	CMOS	General purpose I/O.
	CPS10	AN	—	Capacitive sensing input 10.

Legend: AN = Analog input or output CMOS = CMOS compatible input or output OD = Open Drain
TTL = TTL compatible input ST = Schmitt Trigger input with CMOS levels I^2C = Schmitt Trigger input with I^2C
HV = High Voltage XTAL = Crystal levels

FIGURE 2-3: PROGRAM MEMORY MAP AND STACK FOR THE PIC16F726/LF726 AND PIC16F727/LF727



2.2 Data Memory Organization

The data memory is partitioned into multiple banks which contain the General Purpose Registers (GPRs) and the Special Function Registers (SFRs). Bits RP0 and RP1 are bank select bits.

RP1	RP0		
0	0	→	Bank 0 is selected
0	1	→	Bank 1 is selected
1	0	→	Bank 2 is selected
1	1	→	Bank 3 is selected

Each bank extends up to 7Fh (128 bytes). The lower locations of each bank are reserved for the Special Function Registers. Above the Special Function Registers are the General Purpose Registers, implemented as static RAM. All implemented banks contain Special Function Registers. Some frequently used Special Function Registers from one bank are mirrored in another bank for code reduction and quicker access.

2.2.1 GENERAL PURPOSE REGISTER FILE

The register file is organized as 128 x 8 bits in the PIC16F722/LF722, 192 x 8 bits in the PIC16F723/LF723 and PIC16F724/LF724, and 368 x 8 bits in the PIC16F726/LF726 and PIC16F727/LF727. Each register is accessed either directly or indirectly through the File Select Register (FSR), (Refer to **Section 2.5 "Indirect Addressing, INDF and FSR Registers"**).

2.2.2 SPECIAL FUNCTION REGISTERS

The Special Function Registers are registers used by the CPU and peripheral functions for controlling the desired operation of the device (refer to Table 2-1). These registers are static RAM.

The Special Function Registers can be classified into two sets: core and peripheral. The Special Function Registers associated with the "core" are described in this section. Those related to the operation of the peripheral features are described in the section of that peripheral feature.

FIGURE 6-7: BLOCK DIAGRAM OF RB0

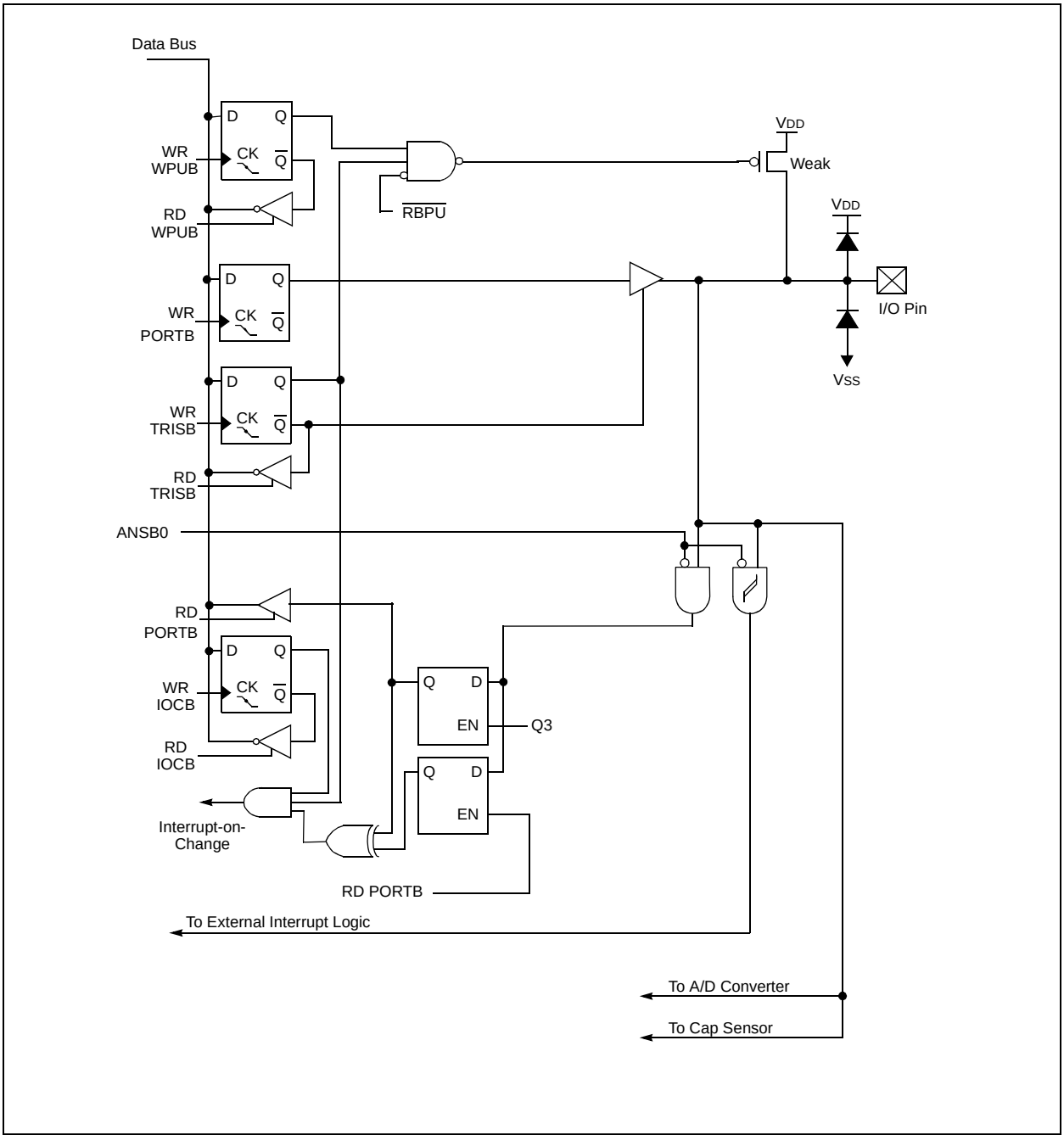
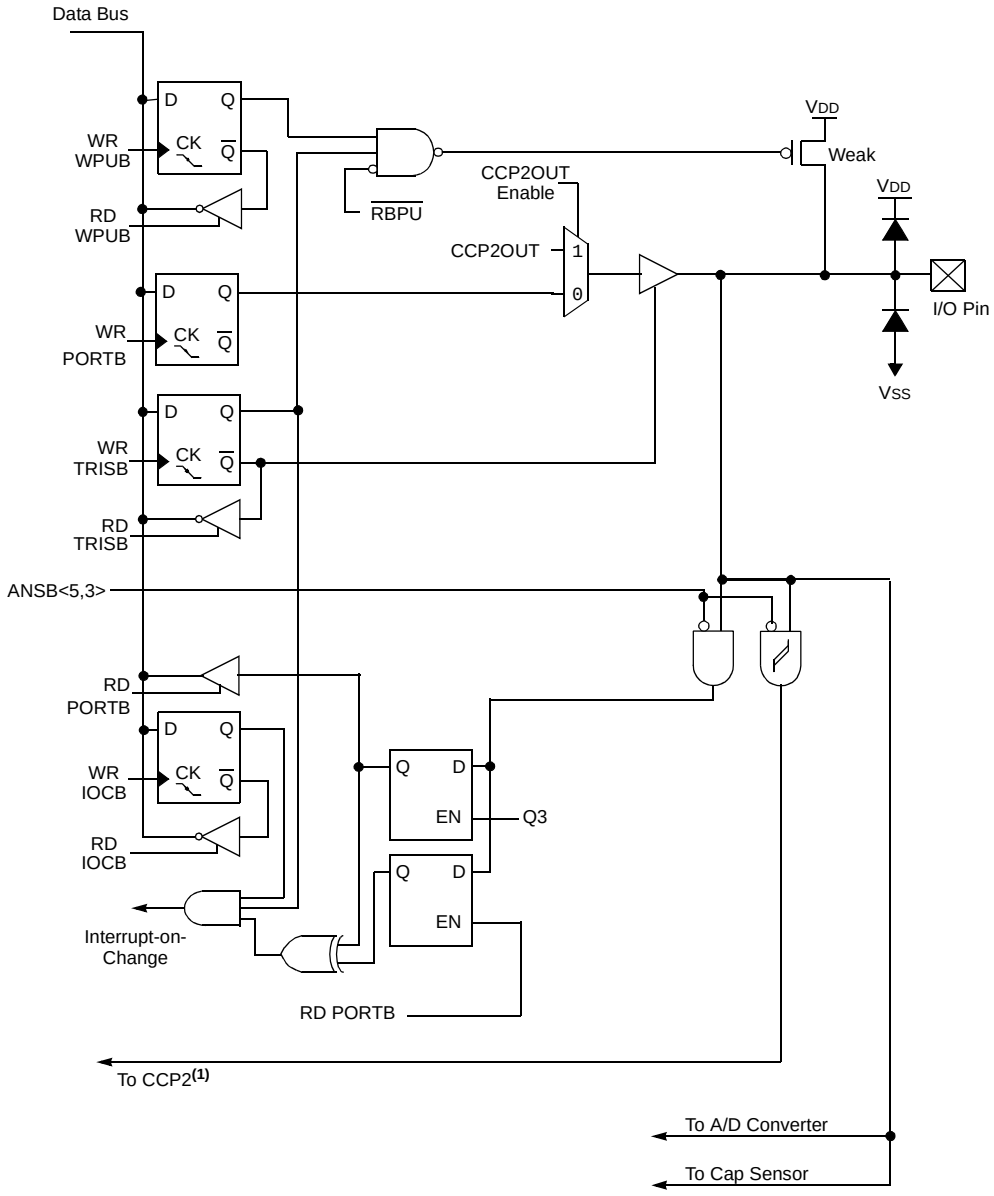


FIGURE 6-9: BLOCK DIAGRAM OF RB3



Note 1: CCP2 input is controlled by CCP2SEL in the APFCON register.

6.4.1 RC0/T1OSO/T1CKI

Figure 6-13 shows the diagram for this pin. This pin is configurable to function as one of the following:

- a general purpose I/O
- a Timer1 oscillator output
- a Timer1 clock input

6.4.2 RC1/T1OSI/CCP2

Figure 6-14 shows the diagram for this pin. This pin is configurable to function as one of the following:

- a general purpose I/O
- a Timer1 oscillator input
- a Capture 2 input, Compare 2 output, and PWM2 output

Note:	CCP2 pin location may be selected as RB3 or RC1.

6.4.3 RC2/CCP1

Figure 6-15 shows the diagram for this pin. This pin is configurable to function as one of the following:

- a general purpose I/O
- a Capture 1 input, Compare 1 output, and PWM1 output

6.4.4 RC3/SCK/SCL

Figure 6-16 shows the diagram for this pin. This pin is configurable to function as one of the following:

- a general purpose I/O
- a SPI clock
- an I^2C clock

6.4.5 RC4/SDI/SDA

Figure 6-17 shows the diagram for this pin. This pin is configurable to function as one of the following:

- a general purpose I/O
- a SPI data input
- an I^2C data I/O

6.4.6 RC5/SDO

Figure 6-18 shows the diagram for this pin. This pin is configurable to function as one of the following:

- a general purpose I/O
- a SPI data output

6.4.7 RC6/TX/CK

Figure 6-19 shows the diagram for this pin. This pin is configurable to function as one of the following:

- a general purpose I/O
- an asynchronous serial output
- a synchronous clock I/O

6.4.8 RC7/RX/DT

Figure 6-20 shows the diagram for this pin. This pin is configurable to function as one of the following:

- a general purpose I/O
- an asynchronous serial input
- a synchronous serial data I/O

8.2 Code Protection

If the code protection bit(s) have not been programmed, the on-chip program memory can be read out using ICSP™ for verification purposes.

Note:	The entire Flash program memory will be erased when the code protection is turned off. See the "*PIC16(L)F72X Memory Programming Specification*" (DS41332) for more information.

8.3 User ID

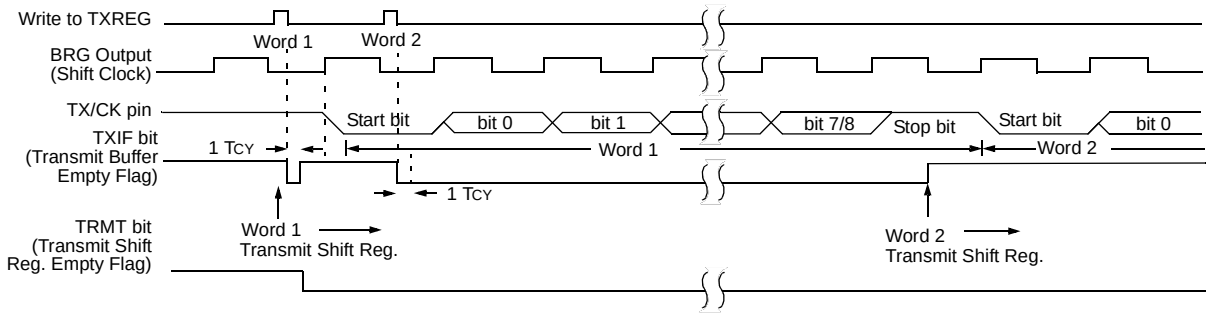
Four memory locations (2000h-2003h) are designated as ID locations where the user can store checksum or other code identification numbers. These locations are not accessible during normal execution, but are readable and writable during Program/Verify mode. Only the Least Significant seven bits of the ID locations are reported when using MPLAB IDE. See the "*PIC16(L)F72X Memory Programming Specification*" (DS41332) for more information.

TABLE 15-3: SUMMARY OF REGISTERS ASSOCIATED WITH CAPTURE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
ANSELB	—	—	ANSB5	ANSB4	ANSB3	ANSB2	ANSB1	ANSB0	--11 1111	--11 1111
APFCON	—	—	—	—	—	—	SSSEL	CCP2SEL	---- --00	---- --00
CCP1CON	—	—	DC1B1	DC1B0	CCP1M3	CCP1M2	CCP1M1	CCP1M0	--00 0000	--00 0000
CCP2CON	—	—	DC2B1	DC2B0	CCP2M3	CCP2M2	CCP2M1	CCP2M0	--00 0000	--00 0000
CCPRxL	Capture/Compare/PWM Register X Low Byte								xxxx xxxx	uuuu uuuu
CCPRxH	Capture/Compare/PWM Register X High Byte								xxxx xxxx	uuuu uuuu
INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000x
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
PIE2	—	—	—	—	—	—	—	CCP2IE	---- ---0	---- ---0
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
PIR2	—	—	—	—	—	—	—	CCP2IF	---- ---0	---- ---0
T1CON	TMR1CS1	TMR1CS0	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{\text{T1SYNC}}$	—	TMR1ON	0000 00-0	uuuu uu-u
T1GCON	TMR1GE	T1GPOL	T1GTM	T1GSPM	T1GGO/$\overline{\text{DONE}}$	T1GVAL	T1GSS1	T1GSS0	0000 0x00	0000 0x00
TMR1L	Holding Register for the Least Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
TMR1H	Holding Register for the Most Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	1111 1111	1111 1111
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	1111 1111	1111 1111

Legend: - = Unimplemented locations, read as '0', u = unchanged, x = unknown. Shaded cells are not used by the Capture.

FIGURE 16-4: ASYNCHRONOUS TRANSMISSION (BACK-TO-BACK)



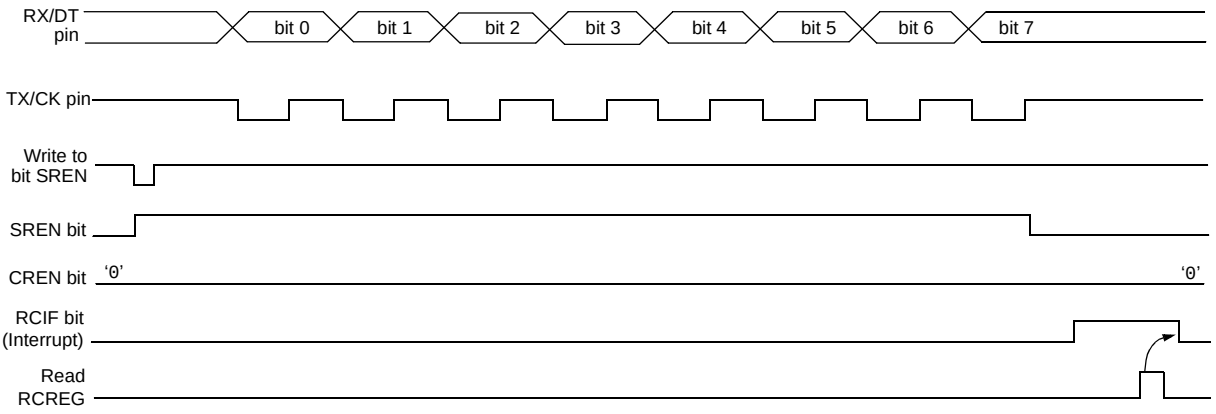
Note: This timing diagram shows two consecutive transmissions.

TABLE 16-1: REGISTERS ASSOCIATED WITH ASYNCHRONOUS TRANSMISSION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000x
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	0000 000x	0000 000x
SPBRG	BRG7	BRG6	BRG5	BRG4	BRG3	BRG2	BRG1	BRG0	0000 0000	0000 0000
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	1111 1111	1111 1111
TXREG	AUSART Transmit Data Register								0000 0000	0000 0000
TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	0000 -010

Legend: x = unknown, - = unimplemented read as '0'. Shaded cells are not used for Asynchronous Transmission.

FIGURE 16-8: SYNCHRONOUS RECEPTION (MASTER MODE, SREN)



Note: Timing diagram demonstrates Synchronous Master mode with bit SREN = 1 and bit BRGH = 0.

TABLE 16-7: REGISTERS ASSOCIATED WITH SYNCHRONOUS MASTER RECEPTION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000x
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
RCREG	AUSART Receive Data Register								0000 0000	0000 0000
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	0000 000X	0000 000X
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	1111 1111	1111 1111
TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	0000 -010

Legend: x = unknown, - = unimplemented read as '0'. Shaded cells are not used for Synchronous Master Reception.

REGISTER 17-3: SSPCON: SYNCHRONOUS SERIAL PORT CONTROL REGISTER (I²C MODE)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **WCOL**: Write Collision Detect bit
- 1 = The SSPBUF register is written while it is still transmitting the previous word (must be cleared in software)
- 0 = No collision

bit 6 **SSPOV**: Receive Overflow Indicator bit
- 1 = A byte is received while the SSPBUF register is still holding the previous byte. SSPOV is a "don't care" in Transmit mode. SSPOV must be cleared in software in either mode.
- 0 = No overflow

bit 5 **SSPEN**: Synchronous Serial Port Enable bit
- 1 = Enables the serial port and configures the SDA and SCL pins as serial port pins **(2)**
- 0 = Disables serial port and configures these pins as I/O port pins

bit 4 **CKP**: Clock Polarity Select bit
- 1 = Release control of SCL
- 0 = Holds clock low (clock stretch). (Used to ensure data setup time.)

bit 3-0 **SSPM<3:0>**: Synchronous Serial Port Mode Select bits
- 0110 = I²C Slave mode, 7-bit address
- 0111 = I²C Slave mode, 10-bit address
- 1000 = Reserved
- 1001 = Load SSPMSK register at SSPADD SFR Address **(1)**
- 1010 = Reserved
- 1011 = I²C Firmware Controlled Master mode (Slave Idle)
- 1100 = Reserved
- 1101 = Reserved
- 1110 = I²C Slave mode, 7-bit address with Start and Stop bit interrupts enabled
- 1111 = I²C Slave mode, 10-bit address with Start and Stop bit interrupts enabled

Note 1: When this mode is selected, any reads or writes to the SSPADD SFR address accesses the SSPMSK register.

2: When enabled, these pins must be properly configured as input or output using the associated TRIS bit.

20.0 IN-CIRCUIT SERIAL PROGRAMMING™ (ICSP™)

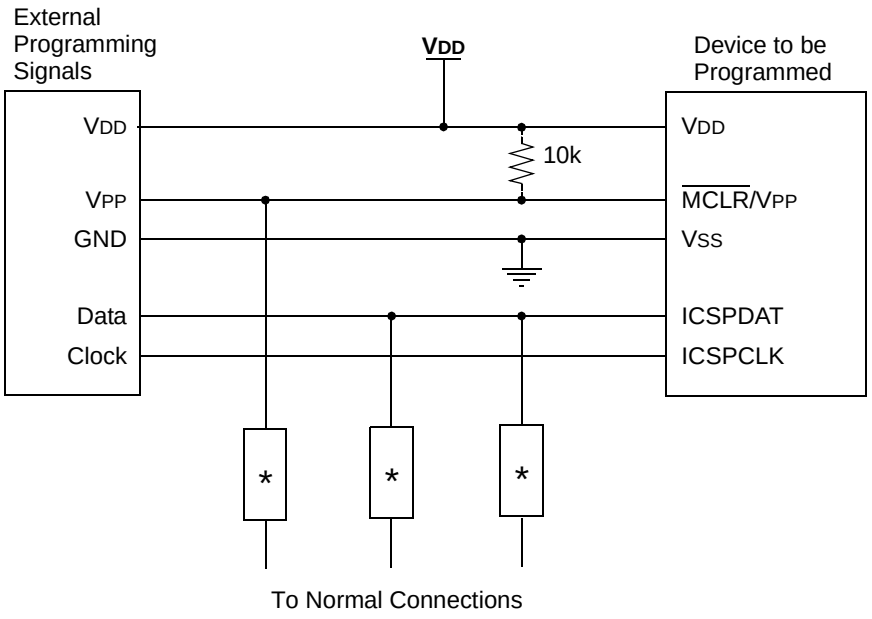
ICSP™ programming allows customers to manufacture circuit boards with unprogrammed devices. Programming can be done after the assembly process allowing the device to be programmed with the most recent firmware or a custom firmware. Five pins are needed for ICSP™ programming:

- ICSPCLK
- ICSPDAT
- MCLR/VPP
- VDD
- VSS

The device is placed into Program/Verify mode by holding the ICSPCLK and ICSPDAT pins low then raising the voltage on MCLR/VPP from 0v to VPP. In Program/Verify mode the program memory, User IDs and the Configuration Words are programmed through serial communications. The ICSPDAT pin is a bidirectional I/O used for transferring the serial data and the ISCPCLK pin is the clock input. For more information on ICSP, refer to the *"PIC16(L)F72x Memory Programming Specification"* (DS41332).

Note:	The ICD 2 produces a VPP voltage greater than the maximum VPP specification of the PIC16(L)F722/3/4/6/7. When using this programmer, an external circuit, such as the AC164112 MPLAB ICD 2 VPP voltage limiter, is required to keep the VPP voltage within the device specifications.

FIGURE 20-1: TYPICAL CONNECTION FOR ICSP™ PROGRAMMING



* Isolation devices (as required).

22.6 MPLAB X SIM Software Simulator

The MPLAB X SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, most peripherals and internal registers.

The MPLAB X SIM Software Simulator fully supports symbolic debugging using the MPLAB XC Compilers, and the MPASM and MPLAB Assemblers. The software simulator offers the flexibility to develop and debug code outside of the hardware laboratory environment, making it an excellent, economical software development tool.

22.7 MPLAB REAL ICE In-Circuit Emulator System

The MPLAB REAL ICE In-Circuit Emulator System is Microchip's next generation high-speed emulator for Microchip Flash DSC and MCU devices. It debugs and programs all 8, 16 and 32-bit MCU, and DSC devices with the easy-to-use, powerful graphical user interface of the MPLAB X IDE.

The emulator is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with either a connector compatible with in-circuit debugger systems (RJ-11) or with the new high-speed, noise tolerant, Low-Voltage Differential Signal (LVDS) interconnection (CAT5).

The emulator is field upgradable through future firmware downloads in MPLAB X IDE. MPLAB REAL ICE offers significant advantages over competitive emulators including full-speed emulation, run-time variable watches, trace analysis, complex breakpoints, logic probes, a ruggedized probe interface and long (up to three meters) interconnection cables.

22.8 MPLAB ICD 3 In-Circuit Debugger System

The MPLAB ICD 3 In-Circuit Debugger System is Microchip's most cost-effective, high-speed hardware debugger/programmer for Microchip Flash DSC and MCU devices. It debugs and programs PIC Flash microcontrollers and dsPIC DSCs with the powerful, yet easy-to-use graphical user interface of the MPLAB IDE.

The MPLAB ICD 3 In-Circuit Debugger probe is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with a connector compatible with the MPLAB ICD 2 or MPLAB REAL ICE systems (RJ-11). MPLAB ICD 3 supports all MPLAB ICD 2 headers.

22.9 PICkit 3 In-Circuit Debugger/ Programmer

The MPLAB PICkit 3 allows debugging and programming of PIC and dsPIC Flash microcontrollers at a most affordable price point using the powerful graphical user interface of the MPLAB IDE. The MPLAB PICkit 3 is connected to the design engineer's PC using a full-speed USB interface and can be connected to the target via a Microchip debug (RJ-11) connector (compatible with MPLAB ICD 3 and MPLAB REAL ICE). The connector uses two device I/O pins and the Reset line to implement in-circuit debugging and In-Circuit Serial Programming™ (ICSP™).

22.10 MPLAB PM3 Device Programmer

The MPLAB PM3 Device Programmer is a universal, CE compliant device programmer with programmable voltage verification at V_{DDMIN} and V_{DDMAX} for maximum reliability. It features a large LCD display (128 x 64) for menus and error messages, and a modular, detachable socket assembly to support various package types. The ICSP cable assembly is included as a standard item. In Stand-Alone mode, the MPLAB PM3 Device Programmer can read, verify and program PIC devices without a PC connection. It can also set code protection in this mode. The MPLAB PM3 connects to the host PC via an RS-232 or USB cable. The MPLAB PM3 has high-speed communications and optimized algorithms for quick programming of large memory devices, and incorporates an MMC card for file storage and data applications.

23.7 AC Characteristics: PIC16F72X-I/E

FIGURE 23-3: CLOCK TIMING

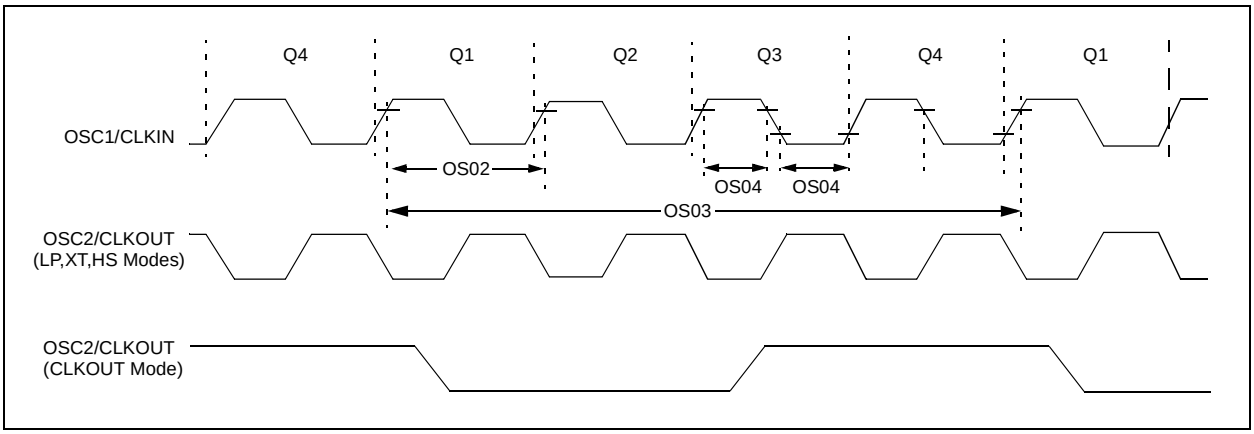
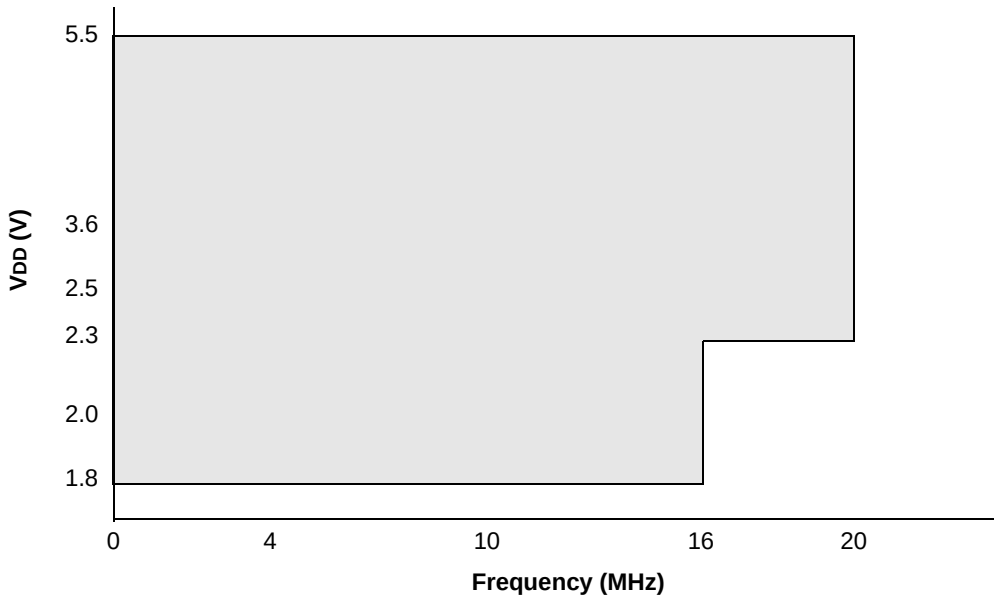
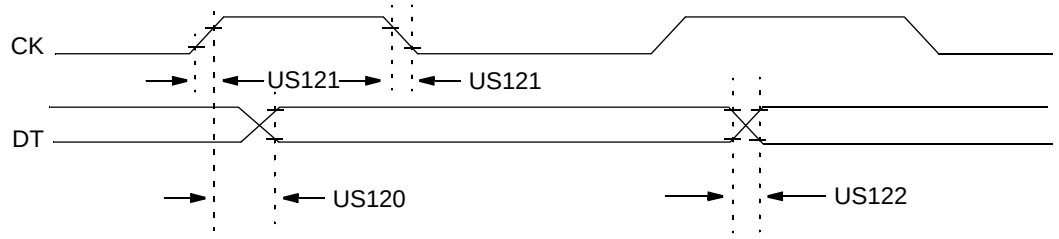


FIGURE 23-4: PIC16F722/3/4/6/7 VOLTAGE FREQUENCY GRAPH, -40°C ≤ TA ≤ +125°C



Note 1: The shaded region indicates the permissible combinations of voltage and frequency.
2: Refer to Table 23-1 for each Oscillator mode's supported frequencies.

FIGURE 23-14: USART SYNCHRONOUS TRANSMISSION (MASTER/SLAVE) TIMING

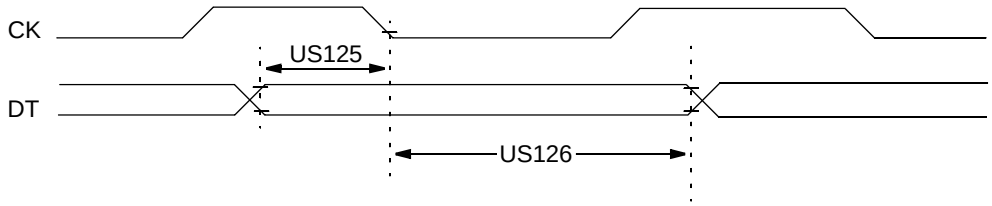


Note: Refer to Figure 23-2 for load conditions.

TABLE 23-9: USART SYNCHRONOUS TRANSMISSION REQUIREMENTS

Standard Operating Conditions (unless otherwise stated) Operating Temperature -40°C ≤ TA ≤ +125°C							
Param. No.	**Symbol**	**Characteristic**		**Min.**	**Max.**	**Units**	**Conditions**
US120	TCKH2DTV	SYNC XMIT (Master and Slave) Clock high to data-out valid	3.0-5.5V	—	80	ns	
			1.8-5.5V	—	100	ns	
US121	TCKRF	Clock out rise time and fall time (Master mode)	3.0-5.5V	—	45	ns	
			1.8-5.5V	—	50	ns	
US122	TDTRF	Data-out rise time and fall time	3.0-5.5V	—	45	ns	
			1.8-5.5V	—	50	ns	

FIGURE 23-15: USART SYNCHRONOUS RECEIVE (MASTER/SLAVE) TIMING



Note: Refer to Figure 23-2 for load conditions.

TABLE 23-10: USART SYNCHRONOUS RECEIVE REQUIREMENTS

Standard Operating Conditions (unless otherwise stated) Operating Temperature -40°C ≤ TA ≤ +125°C						
Param. No.	**Symbol**	**Characteristic**	**Min.**	**Max.**	**Units**	**Conditions**
US125	TDTV2CKL	SYNC RCV (Master and Slave) Data-hold before CK ↓ (DT hold time)	10	—	ns	
US126	TCKL2DTL	Data-hold after CK ↓ (DT hold time)	15	—	ns	

FIGURE 24-39: PIC16F722/3/4/6/7 CAP SENSE LOW POWER IPD vs. VDD, VCAP = 0.1 µF

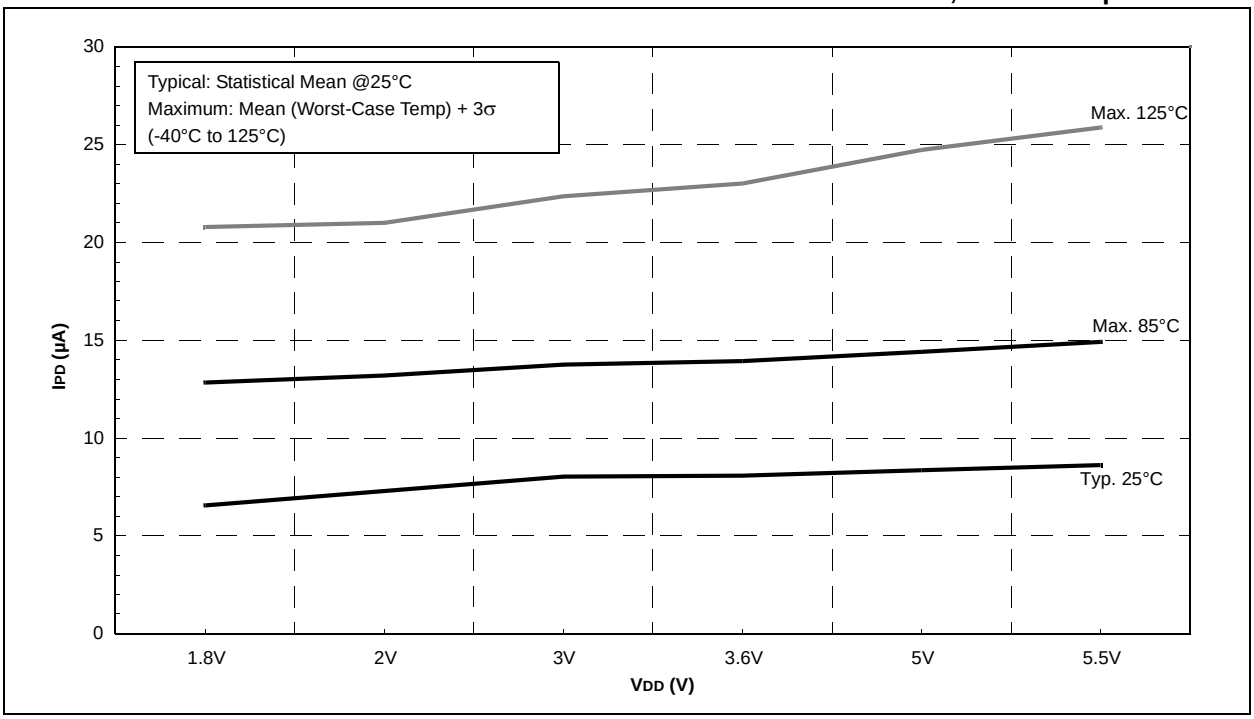


FIGURE 24-40: PIC16LF722/3/4/6/7 CAP SENSE LOW POWER IPD vs. VDD

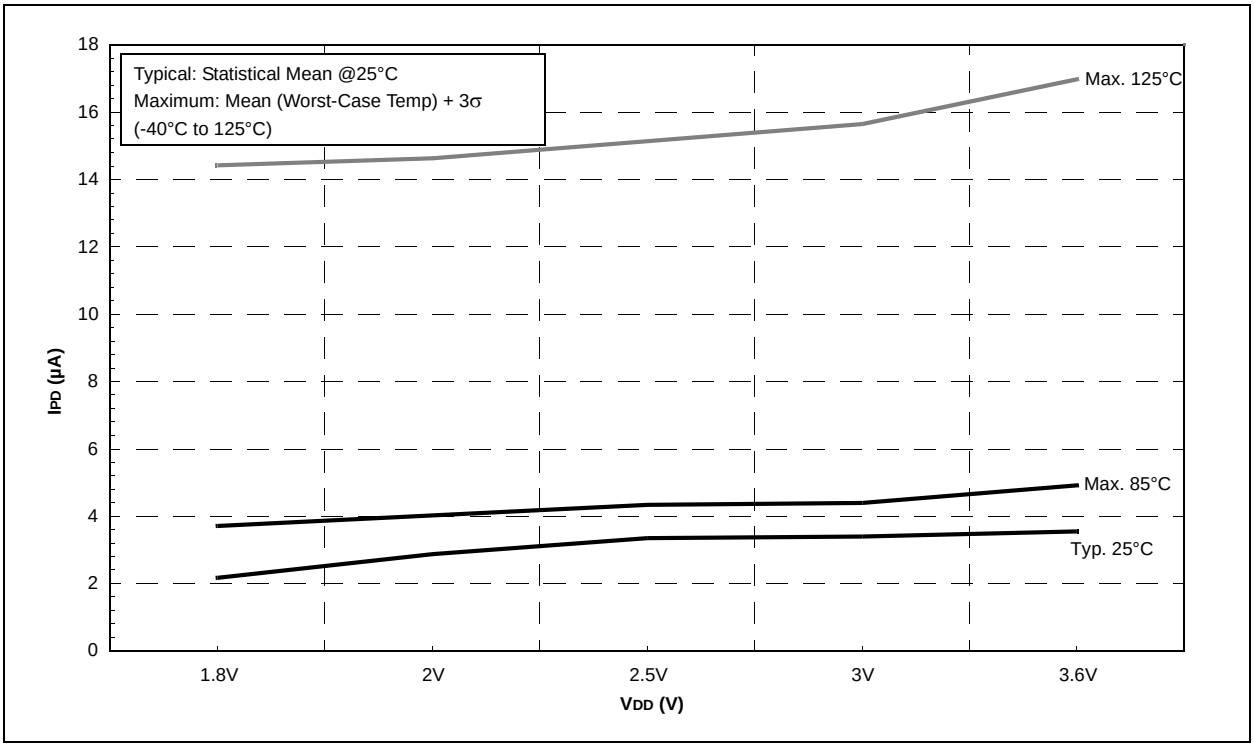


FIGURE 24-41: PIC16F722/3/4/6/7 T1OSC 32 KHZ IPD VS. VDD, VCAP = 0.1 µF

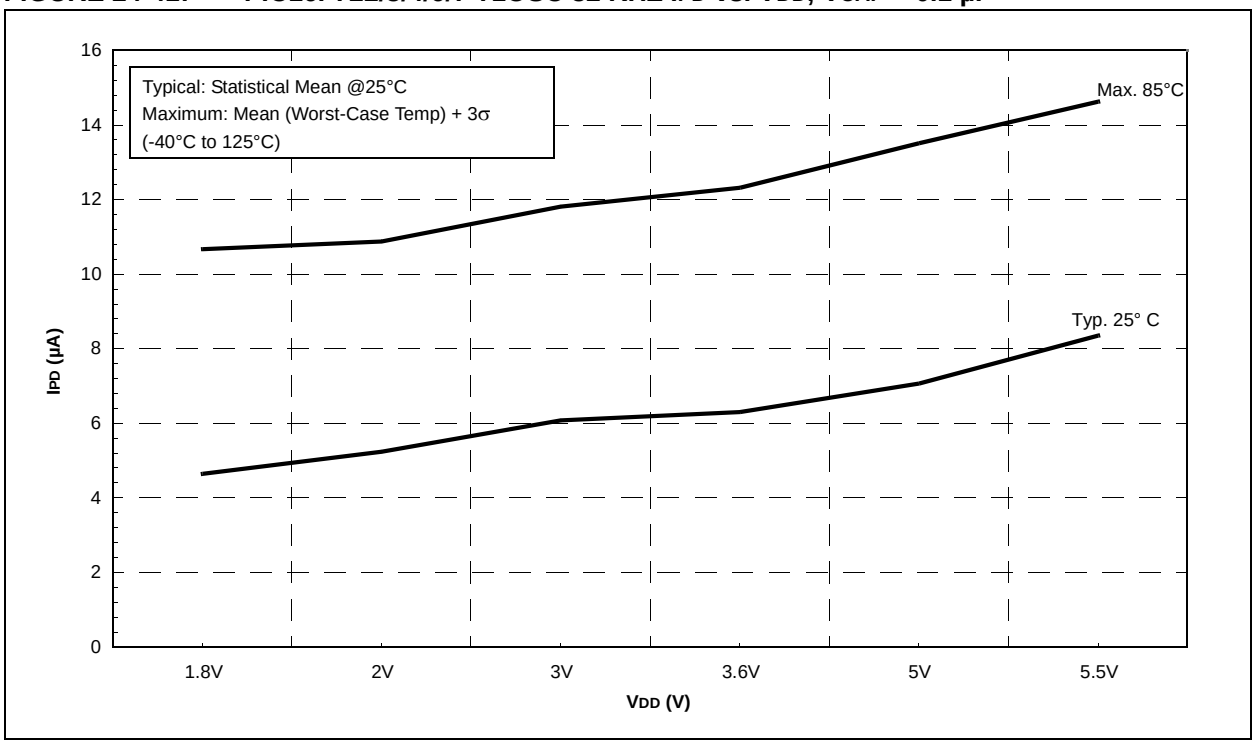
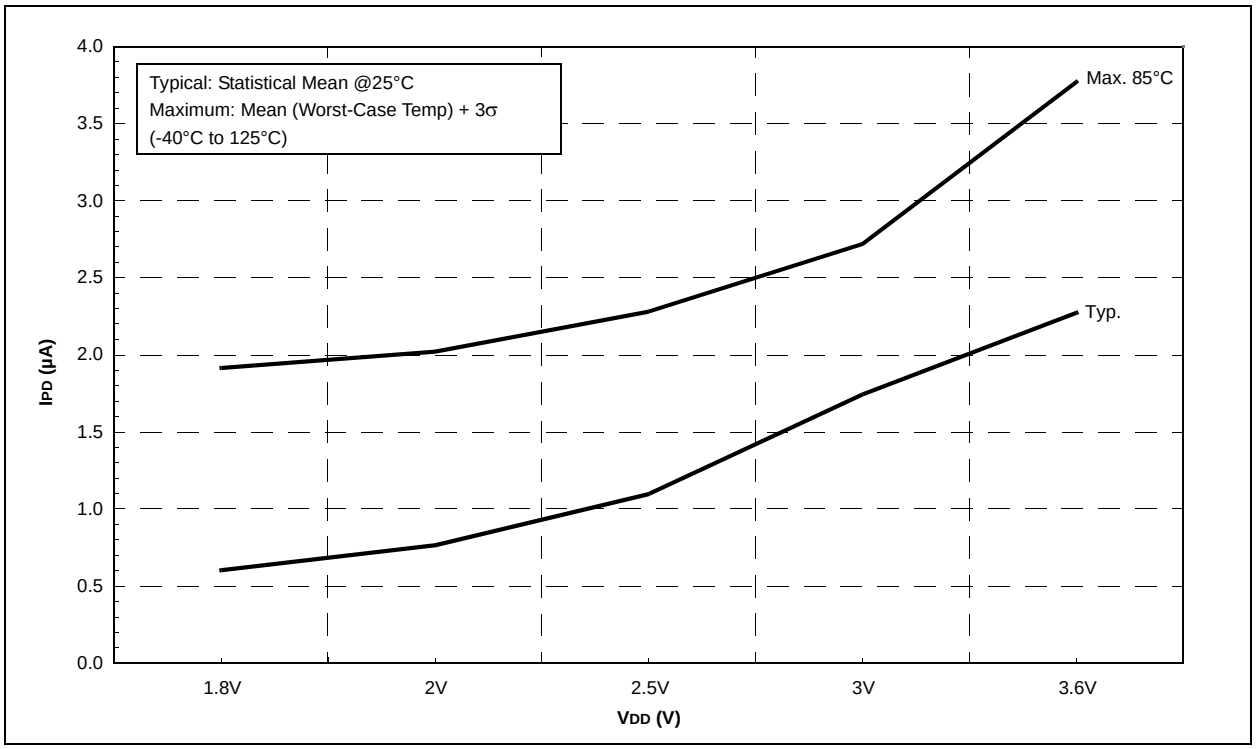
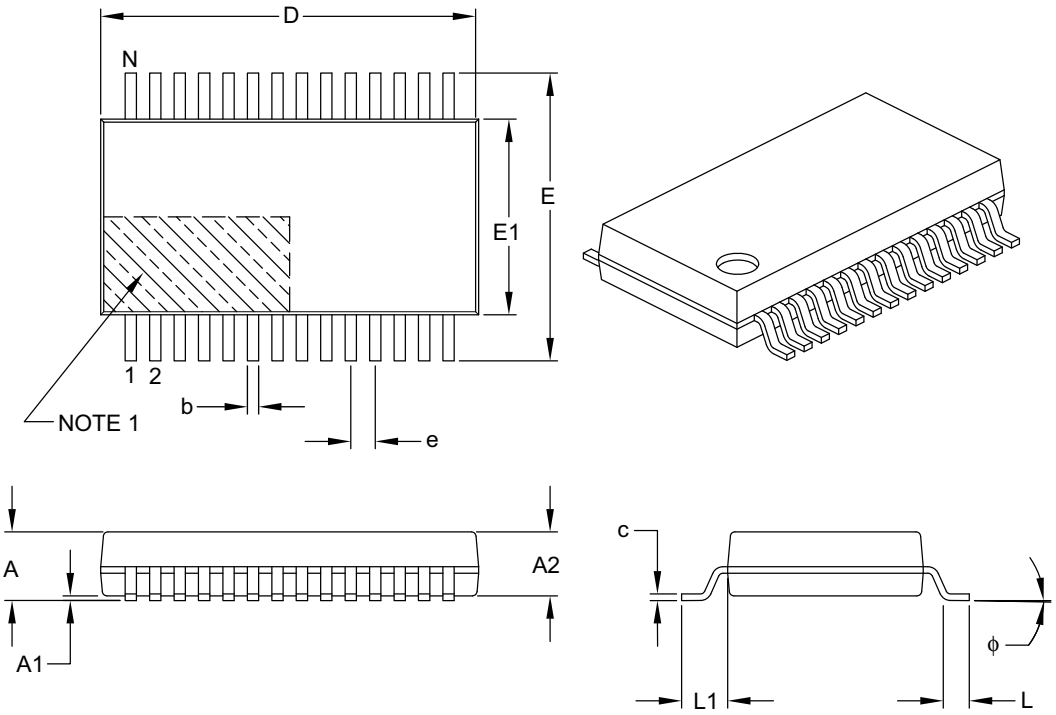


FIGURE 24-42: PIC16LF722/3/4/6/7 T1OSC 32 kHz IPD VS. VDD



28-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		0.65 BSC	
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	9.90	10.20	10.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1		1.25 REF	
Lead Thickness	c	0.09	–	0.25
Foot Angle	ϕ	0°	4°	8°
Lead Width	b	0.22	–	0.38

Notes:

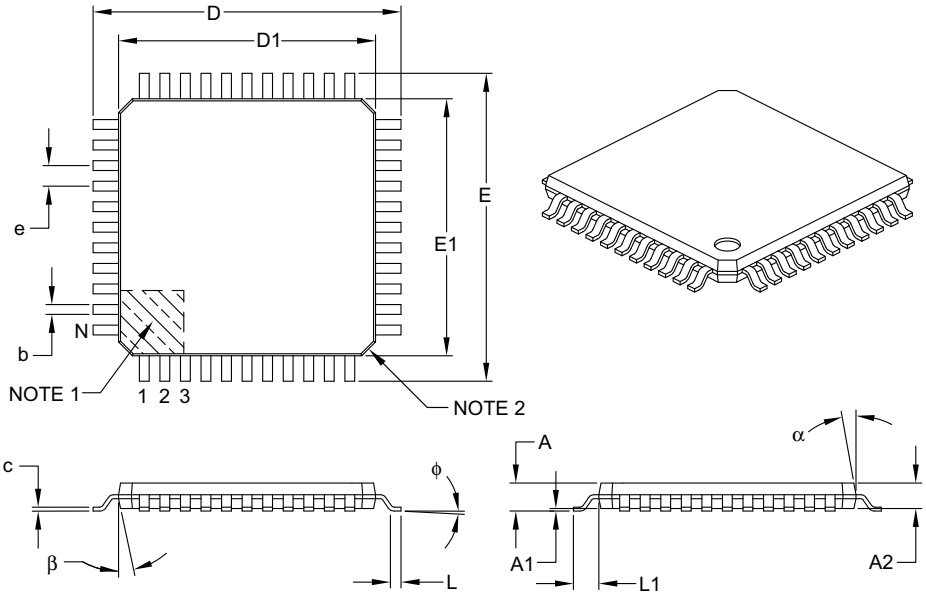
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-073B

44-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		44	
Lead Pitch	e		0.80 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	φ	0°	3.5°	7°
Overall Width	E		12.00 BSC	
Overall Length	D		12.00 BSC	
Molded Package Width	E1		10.00 BSC	
Molded Package Length	D1		10.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.30	0.37	0.45
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

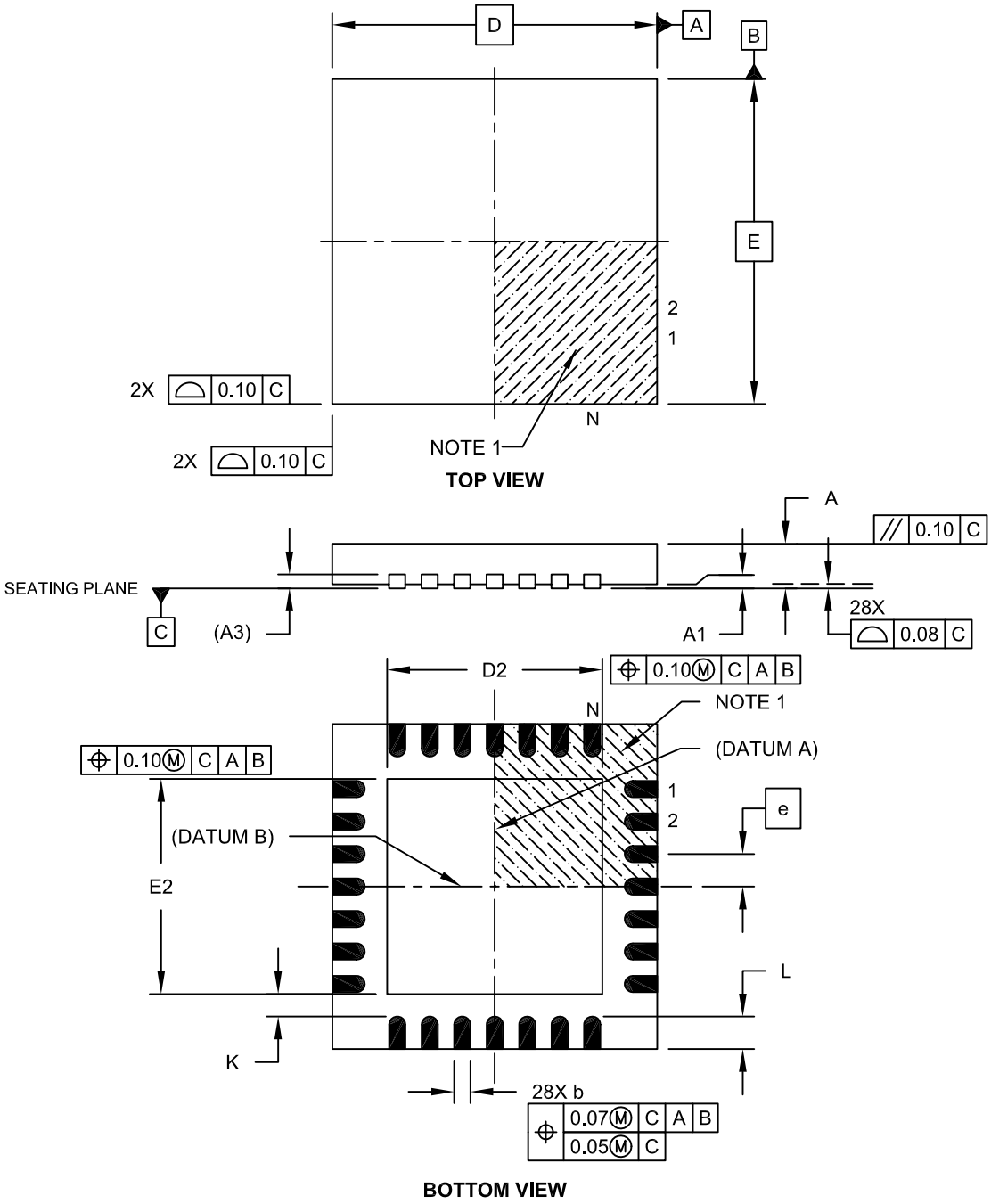
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-076B

28-Lead Plastic Ultra Thin Quad Flat, No Lead Package (MV) – 4x4x0.5 mm Body [UQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-152A Sheet 1 of 2